

Features

- High speed
 - $t_{AA} = 15 \text{ ns}$
- CMOS for optimum speed/power
- Low active power
 - 495 mW
- Low standby power
 - 275 mW
- 2.0V data retention (optional)
- Automatic power down when deselected
- TTL-compatible inputs and outputs

Functional Description

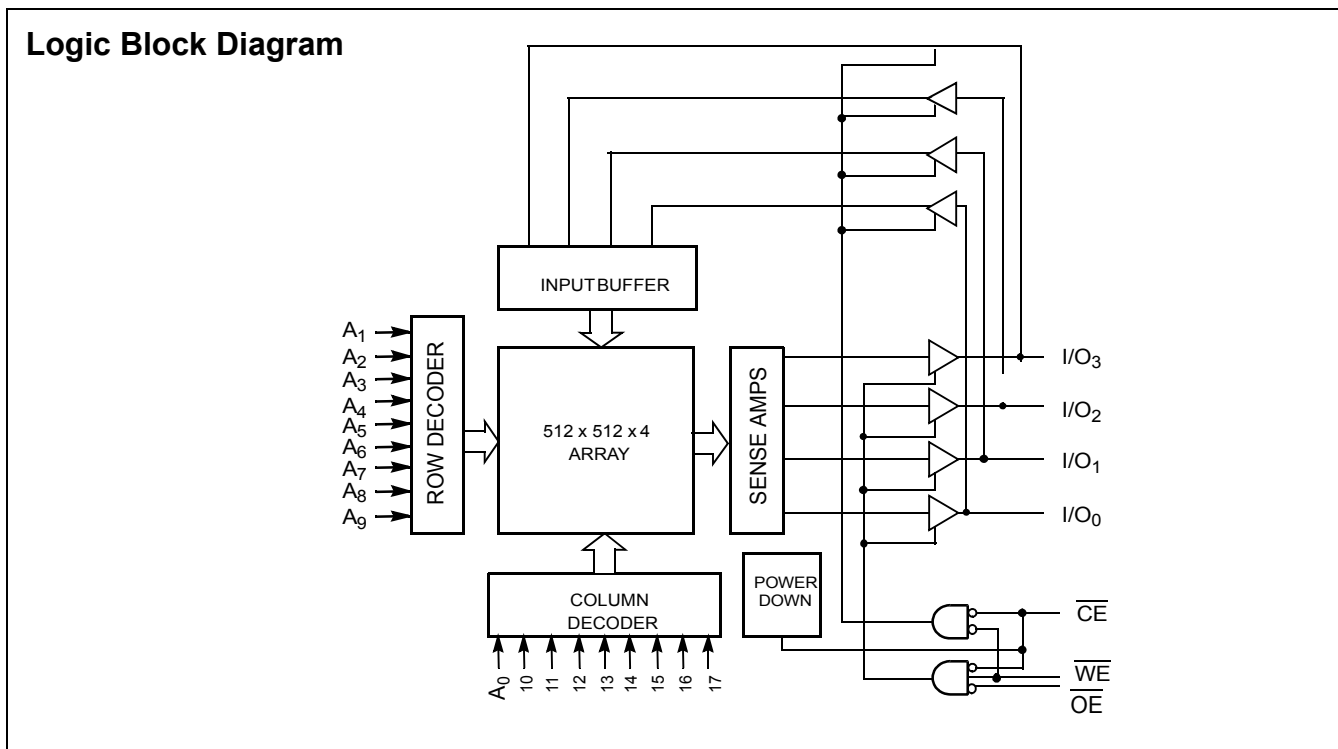
The CY7C106BN is a high performance CMOS static RAMs organized as 262,144 words by 4 bits. Easy memory expansion is provided by an active LOW Chip Enable (\overline{CE}), an active LOW Output Enable (\overline{OE}), and tristate drivers. These devices have an automatic power down feature that reduces power consumption by more than 65% when the devices are deselected.

Writing to the devices is accomplished by taking Chip Enable (\overline{CE}) and Write Enable (\overline{WE}) inputs LOW. Data on the four I/O pins (I/O_0 through I/O_3) is then written into the location specified on the address pins (A_0 through A_{17}).

Reading from the devices is accomplished by taking Chip Enable (\overline{CE}) and Output Enable (\overline{OE}) LOW while forcing Write Enable (\overline{WE}) HIGH. Under these conditions, the contents of the memory location specified by the address pins will appear on the four I/O pins.

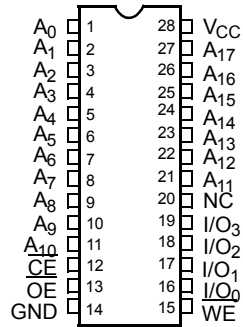
The four input/output pins (I/O_0 through I/O_3) are placed in a high impedance state when the devices are deselected (\overline{CE} HIGH), the outputs are disabled (\overline{OE} HIGH), or during a write operation (\overline{CE} and \overline{WE} LOW).

The CY7C106BN is available in a standard 400-mil-wide SOJ.



Pin Configuration

Figure 1. 28-pin SOJ (Top View)



Selection Guide

Description	7C106BN-15
Maximum Access Time (ns)	15
Maximum Operating Current (mA)	80
Maximum Standby Current (mA)	30

Maximum Ratings

Exceeding the maximum ratings may impair the useful life of the device. These user guidelines are not tested.

- Storage Temperature -65×C to +150×C
- Ambient Temperature with Power Applied -55×C to +125×C
- Supply Voltage on V_{CC} Relative to GND^[1] -0.5V to +7.0V
- DC Voltage Applied to Outputs in High Z State^[1] -0.5V to V_{CC} + 0.5V
- DC Input Voltage^[1] -0.5V to V_{CC} + 0.5V

- Current into Outputs (LOW)..... 20 mA
- Static Discharge Voltage >2001V (per MIL-STD-883, Method 3015)
- Latch Up Current >200 mA

Operating Range

Range	Ambient Temperature ^[2]	V _{CC}
Commercial	0°C to +70°C	5V ± 10%

Electrical Characteristics Over the Operating Range

Parameter	Description	Test Conditions	7C106BN-15		
			Min	Max	Unit
V _{OH}	Output HIGH Voltage	V _{CC} = Min, I _{OH} = -4.0 mA	2.4		V
V _{OL}	Output LOW Voltage	V _{CC} = Min, I _{OL} = 8.0 mA		0.4	V
V _{IH}	Input HIGH Voltage		2.2	V _{CC} + 0.3	V
V _{IL}	Input LOW Voltage ^[1]		-0.3	0.8	V
I _{IX}	Input Leakage Current	GND ≤ V _I ≤ V _{CC}	-1	+1	mA
I _{OZ}	Output Leakage Current	GND ≤ V _I ≤ V _{CC} , Output Disabled	-5	+5	mA
I _{OS}	Output Short Circuit Current ^[3]	V _{CC} = Max, V _{OUT} = GND		-300	mA
I _{CC}	V _{CC} Operating Supply Current	V _{CC} = Max, I _{OUT} = 0 mA, f = f _{MAX} = 1/t _{RC}		80	mA
I _{SB1}	Automatic CE Power Down Current —TTL Inputs	Max V _{CC} , $\overline{CE} \geq V_{IH}$, V _{IN} ≥ V _{IH} or V _{IN} ≤ V _{IL} , f = f _{MAX}		30	mA
I _{SB2}	Automatic CE Power Down Current —CMOS Inputs	Max V _{CC} , $\overline{CE} \geq V_{CC} - 0.3V$, V _{IN} ≥ V _{CC} - 0.3V or V _{IN} ≤ 0.3V, f=0	Commercial	10	mA

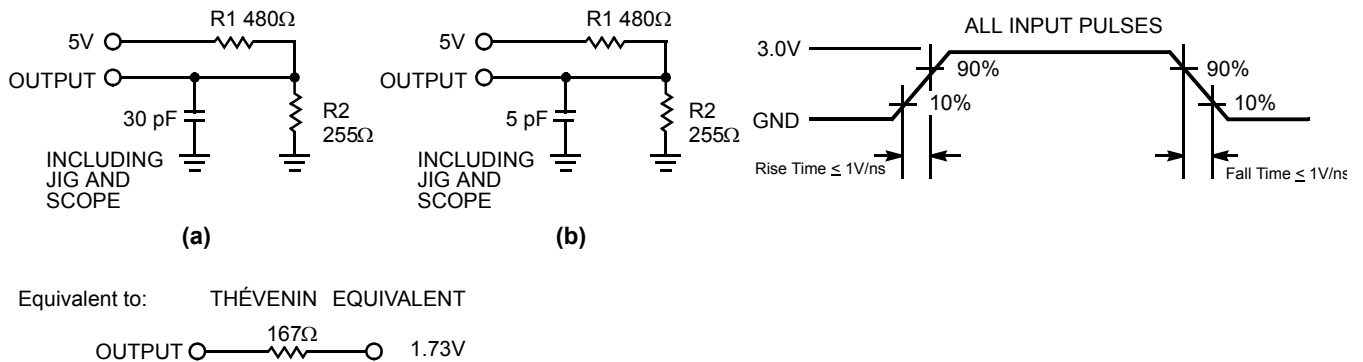
Capacitance^[4]

Parameter	Description	Test Conditions	Max	Unit
C _{IN} : Addresses	Input Capacitance	T _A = 25×C, f = 1 MHz, V _{CC} = 5.0V	7	pF
C _{IN} : Controls			10	pF
C _{OUT}	Output Capacitance		10	pF

Notes

1. V_{IL} (min.) = -2.0V for pulse durations of less than 20 ns.
2. T_A is the "instant on" case temperature.
3. Not more than 1 output should be shorted at one time. Duration of the short circuit should not exceed 30 seconds.
4. Tested initially and after any design or process changes that may affect these parameters.

Figure 2. AC Test Loads and Waveforms



Switching Characteristics Over the Operating Range^[5]

Parameter	Description	7C106B-15		Unit
		Min	Max	
READ CYCLE				
t_{RC}	Read Cycle Time	15		ns
t_{AA}	Address to Data Valid		15	ns
t_{OHA}	Data Hold from Address Change	3		ns
t_{ACE}	\overline{CE} LOW to Data Valid		15	ns
t_{DOE}	\overline{OE} LOW to Data Valid		7	ns
t_{LZOE}	\overline{OE} LOW to Low Z	0		ns
t_{HZOE}	\overline{OE} HIGH to High Z ^[6, 7]		7	ns
t_{LZCE}	\overline{CE} LOW to Low Z ^[7]	3		ns
t_{HZCE}	\overline{CE} HIGH to High Z ^[6, 7]		7	ns
t_{PU}	\overline{CE} LOW to Power Up	0		ns
t_{PD}	\overline{CE} HIGH to Power Down		15	ns
WRITE CYCLE^[8, 9]				
t_{WC}	Write Cycle Time	15		ns
t_{SCE}	\overline{CE} LOW to Write End	12		ns
t_{AW}	Address Setup to Write End	12		ns
t_{HA}	Address Hold from Write End	0		ns
t_{SA}	Address Setup to Write Start	0		ns
t_{PWE}	WE Pulse Width	12		ns
t_{SD}	Data Setup to Write End	8		ns
t_{HD}	Data Hold from Write End	0		ns
t_{LZWE}	WE HIGH to Low Z ^[7]	3		ns
t_{HZWE}	WE LOW to High Z ^[6, 7]		7	ns

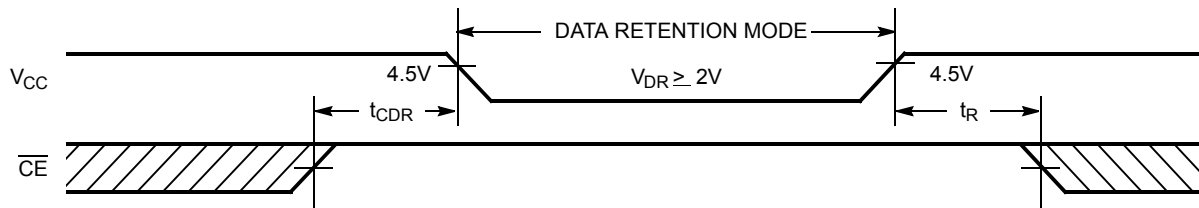
Notes

- Test conditions assume signal transition time of 3 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V, and output loading of the specified I_{OL}/I_{OH} and 30 pF load capacitance.
- t_{HZOE} , t_{HZCE} , and t_{HZWE} are specified with a load capacitance of 5 pF as in part (b) of AC Test Loads. Transition is measured ± 500 mV from steady state voltage.
- At any given temperature and voltage condition, t_{HZCE} is less than t_{LZCE} , t_{HZOE} is less than t_{LZOE} , and t_{HZWE} is less than t_{LZWE} for any given device.
- The internal write time of the memory is defined by the overlap of \overline{CE} and WE LOW. \overline{CE} and WE must be LOW to initiate a write, and the transition of either of these signals can terminate the write. The input data setup and hold timing should be referenced to the leading edge of the signal that terminates the write.
- The minimum write cycle time for Write Cycle No. 3 (WE controlled, \overline{OE} LOW) is the sum of t_{HZWE} and t_{SD} .

Data Retention Characteristics Over the Operating Range

Parameter	Description	Conditions ^[10]	Min	Max	Unit
V _{DR}	V _{CC} for Data Retention		2.0		V
I _{CCDR}	Data Retention Current	V _{CC} = V _{DR} = 2.0V, CE ≥ V _{CC} - 0.3V,		250	μA
t _{CDR} ^[4]	Chip Deselect to Data Retention Time	V _{IN} ≥ V _{CC} - 0.3V or	0		ns
t _R ^[4]	Operation Recovery Time	V _{IN} ≤ 0.3V	200		ms

Figure 3. Data Retention Waveform



Switching Waveforms

Figure 4. Read Cycle No.1^[11, 12]

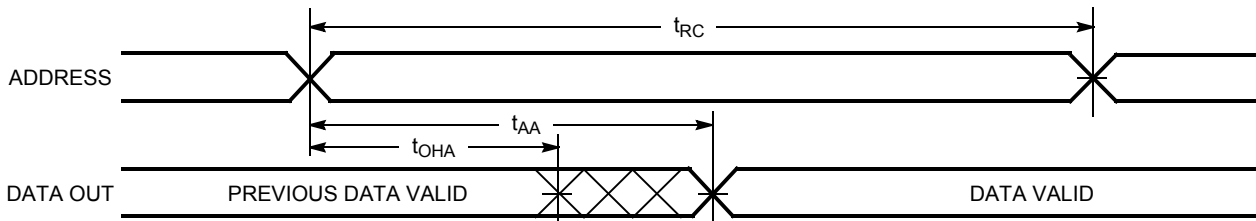
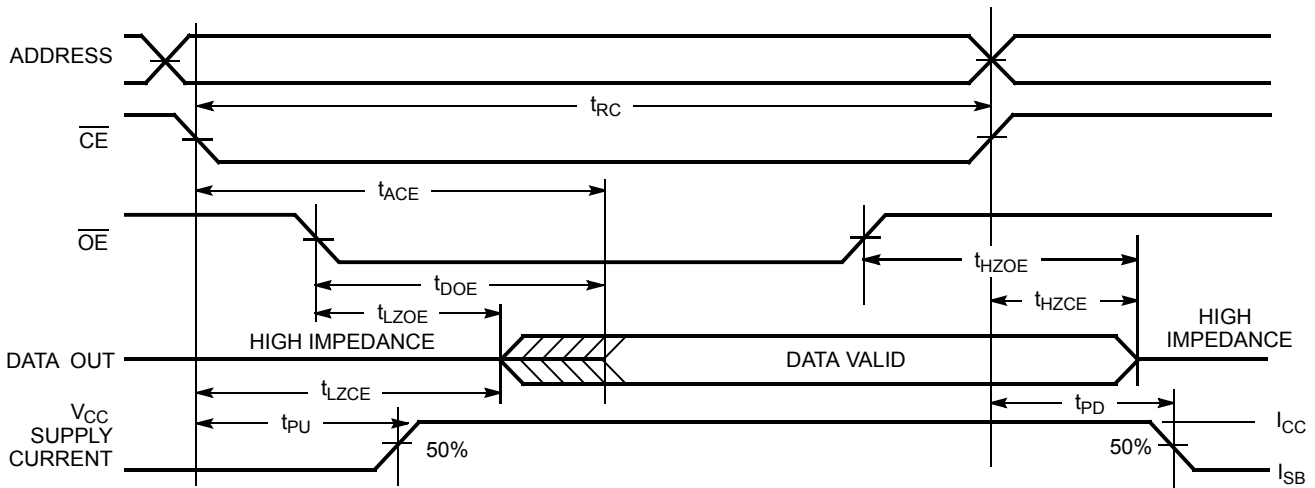


Figure 5. Read Cycle No. 2 (OE Controlled)^[12, 13]



Notes

- 10. No input may exceed V_{CC} +0.5V.
- 11. Device is continuously selected, OE and CE = V_{IL}.
- 12. WE is HIGH for read cycle.
- 13. Address valid prior to or coincident with CE transition LOW.

Switching Waveforms (continued)

Figure 6. Write Cycle No. 1 (\overline{CE} Controlled)^[14, 15]

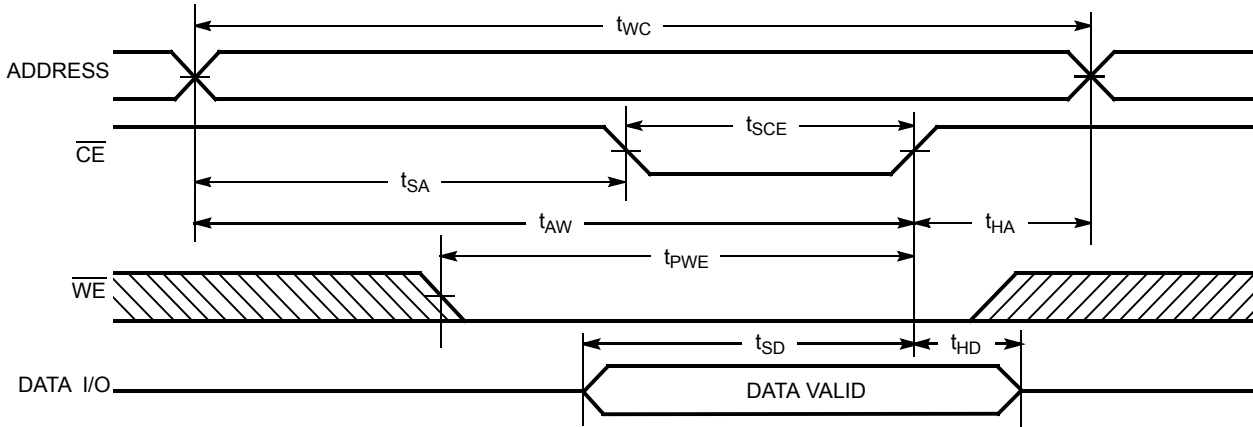
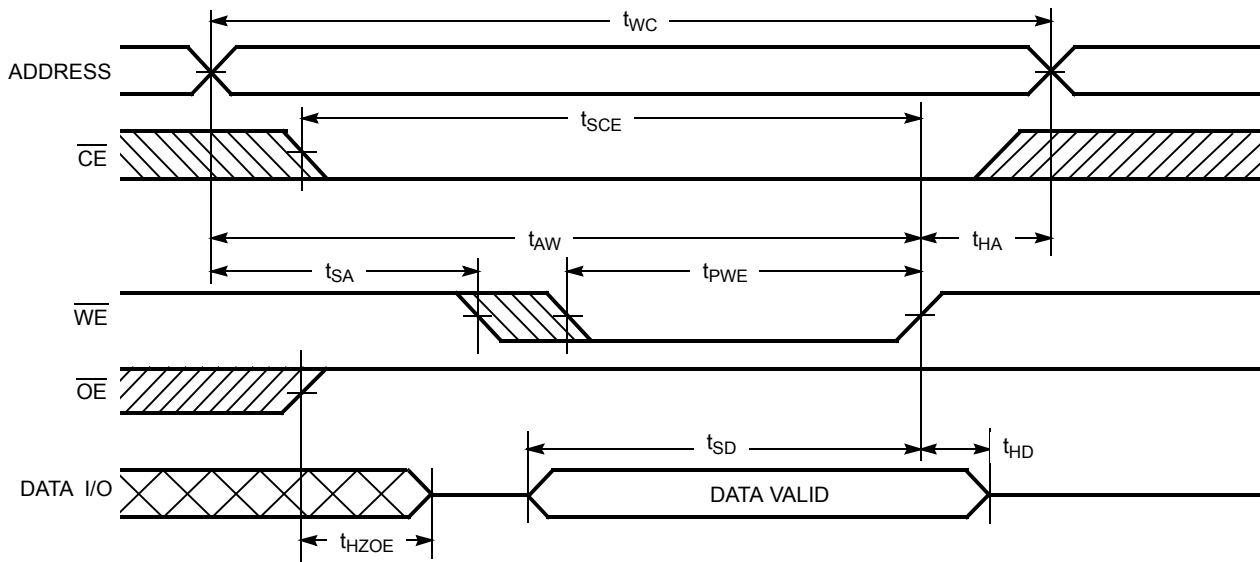


Figure 7. Write Cycle No. 2 (\overline{WE} Controlled, \overline{OE} HIGH During Write)^[14, 15]

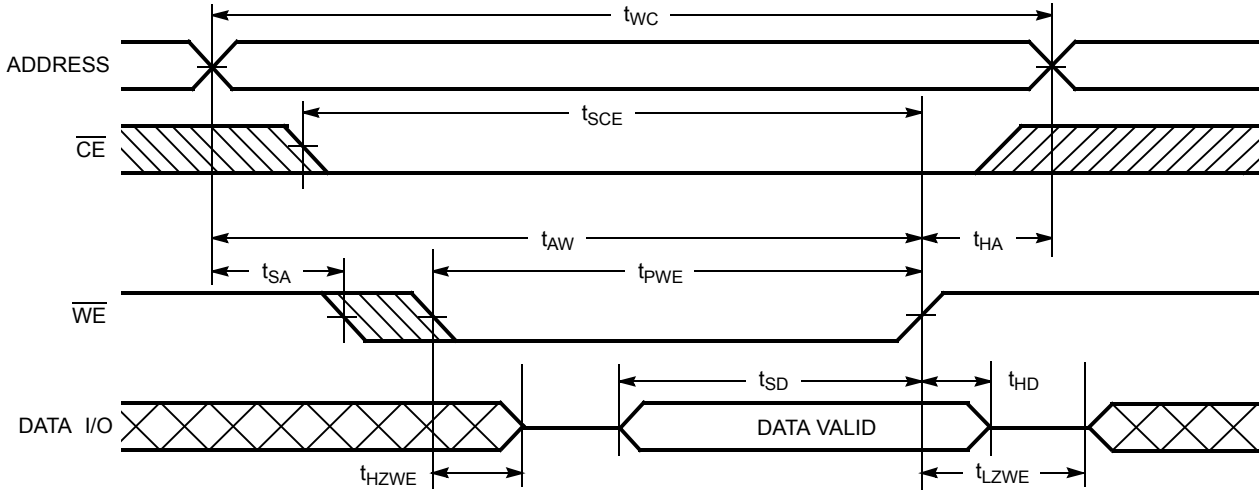


Notes

- 14. If \overline{CE} goes HIGH simultaneously with \overline{WE} going HIGH, the output remains in a high impedance state.
- 15. Data I/O is high impedance if $\overline{OE} = V_{IH}$.

Switching Waveforms (continued)

Figure 8. Write Cycle No. 3 (\overline{WE} Controlled, \overline{OE} LOW)^[9, 15]



Truth Table

CE	OE	WE	Input/Output	Mode	Power
H	X	X	High Z	Power Down	Standby (I _{SB})
L	L	H	Data Out	Read	Active (I _{CC})
L	X	L	Data In	Write	Active (I _{CC})
L	H	H	High Z	Selected, Outputs Disabled	Active (I _{CC})

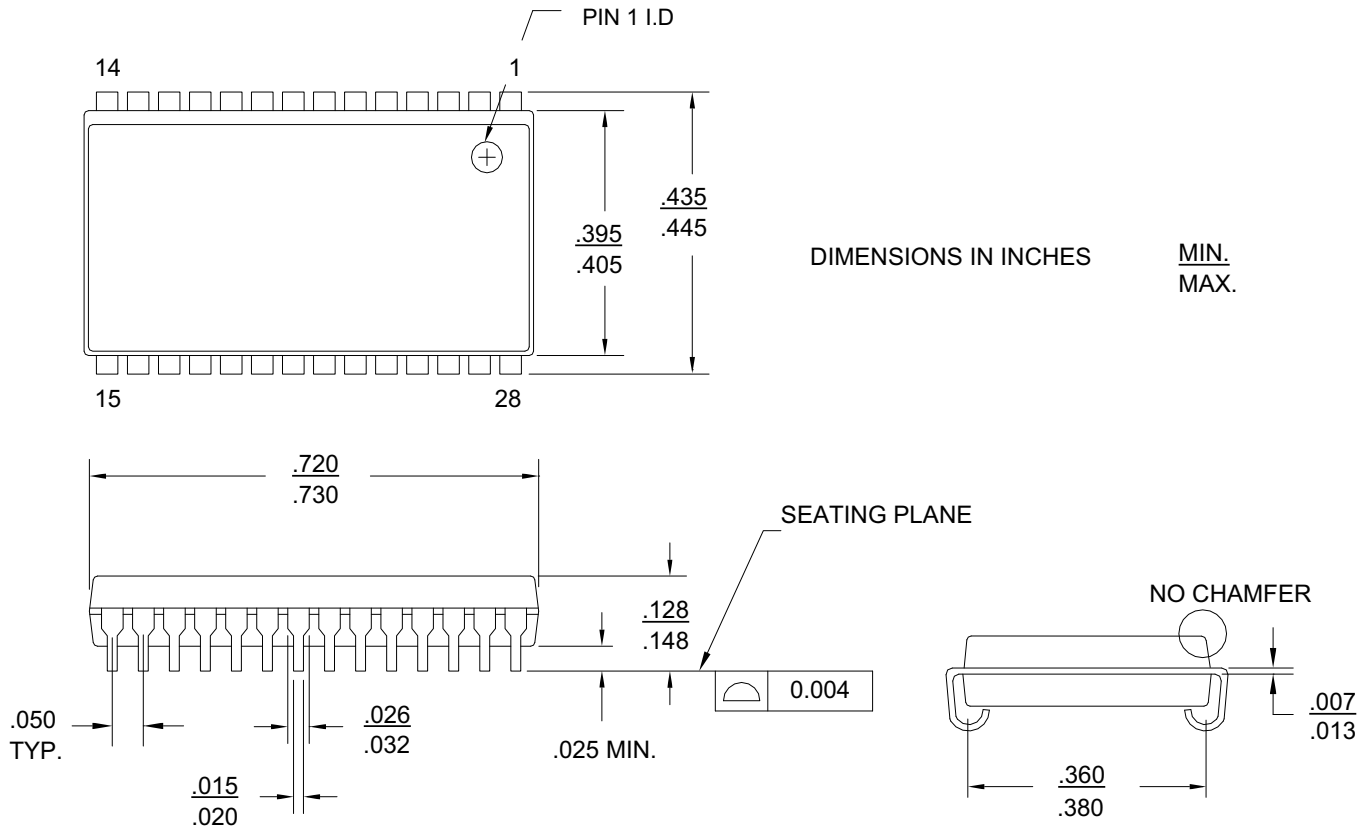
Ordering Information

Speed (ns)	Ordering Code	Package Diagram	Package Type	Operating Range
15	CY7C106BN-15VC	51-85032	28-Pin (400-Mil) Molded SOJ	Commercial

Contact your local sales representative regarding availability of these parts.

Package Diagram

Figure 9. 28-Pin (400 Mil) Molded SOJ



NOTES :

1. PACKAGE WEIGHT : 1.24g
2. JEDEC REFERENCE : MS-027

51-85032.*D

Document History Page

Document Title: CY7C106BN 256K x 4 Static RAM Document Number: 001-06429				
REV.	ECN NO.	Submission Date	Orig. of Change	Description of Change
**	423847	See ECN	NXR	New Data sheet
*A	2891262	03/12/2010	VKN	Removed CY7C1006BN part from the data sheet Removed Industrial grade Removed 20ns speed bin Removed 28-pin (300-Mil) Molded SOJ package Updated POD for 28-pin (400-Mil) Molded SOJ package Updated Ordering information table Updated URLs in Sales, Solutions, and Legal Information

Sales, Solutions, and Legal Information

Worldwide Sales and Design Support

Cypress maintains a worldwide network of offices, solution centers, manufacturer’s representatives, and distributors. To find the office closest to you, visit us at [Cypress Locations](#).

Products

- Automotive cypress.com/go/automotive
- Clocks & Buffers cypress.com/go/clocks
- Interface cypress.com/go/interface
- Lighting & Power Control cypress.com/go/powerpsoc
cypress.com/go/plc
- Memory cypress.com/go/memory
- Optical & Image Sensing cypress.com/go/image
- PSoC cypress.com/go/psoc
- Touch Sensing cypress.com/go/touch
- USB Controllers cypress.com/go/USB
- Wireless/RF cypress.com/go/wireless

PSoC Solutions

- psoc.cypress.com/solutions
- PSoC 1 | PSoC 3 | PSoC 5

© Cypress Semiconductor Corporation, 2006-2010. The information contained herein is subject to change without notice. Cypress Semiconductor Corporation assumes no responsibility for the use of any circuitry other than circuitry embodied in a Cypress product. Nor does it convey or imply any license under patent or other rights. Cypress products are not warranted nor intended to be used for medical, life support, life saving, critical control or safety applications, unless pursuant to an express written agreement with Cypress. Furthermore, Cypress does not authorize its products for use as critical components in life-support systems where a malfunction or failure may reasonably be expected to result in significant injury to the user. The inclusion of Cypress products in life-support systems application implies that the manufacturer assumes all risk of such use and in doing so indemnifies Cypress against all charges.

Any Source Code (software and/or firmware) is owned by Cypress Semiconductor Corporation (Cypress) and is protected by and subject to worldwide patent protection (United States and foreign), United States copyright laws and international treaty provisions. Cypress hereby grants to licensee a personal, non-exclusive, non-transferable license to copy, use, modify, create derivative works of, and compile the Cypress Source Code and derivative works for the sole purpose of creating custom software and or firmware in support of licensee product to be used only in conjunction with a Cypress integrated circuit as specified in the applicable agreement. Any reproduction, modification, translation, compilation, or representation of this Source Code except as specified above is prohibited without the express written permission of Cypress.

Disclaimer: CYPRESS MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARD TO THIS MATERIAL, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE. Cypress reserves the right to make changes without further notice to the materials described herein. Cypress does not assume any liability arising out of the application or use of any product or circuit described herein. Cypress does not authorize its products for use as critical components in life-support systems where a malfunction or failure may reasonably be expected to result in significant injury to the user. The inclusion of Cypress’ product in a life-support systems application implies that the manufacturer assumes all risk of such use and in doing so indemnifies Cypress against all charges.

Use may be limited by and subject to the applicable Cypress software license agreement.